

VS30P60AD-VB Datasheet

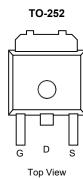
P-Channel 30 V (D-S) MOSFET

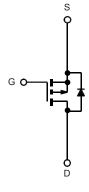
PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a			
- 30	0.009 at V _{GS} = - 10 V	-60			
- 30	0.011 at V _{GS} = - 4.5 V	-58			

FEATURES

Compliant to RoHS Directive 2002/95/EC







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Gate-Source Voltage	V _{GS}	± 20	V			
Continuous Drain Current (T ₁ = 175 °C)	T _C = 25 °C		- 70ª			
	T _C = 125 °C		- 58	A		
Pulsed Drain Current	I _{DM}	- 240	A			
Avalanche Current	I _{AR}	- 60				
Repetitive Avalanche Energy ^b	L = 0.1 mH	E _{AR}	180	mJ		
Power Dissignation	T _C = 25 °C	Р	87 ^d	w		
	T _A = 25 °C	– P _D –	78	vv		
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount		60			
Junction-to-Ambient	Free Air	R _{thJA}	68.5	°C/W		
Junction-to-Case		R _{thJC}	1.0			

Notes:

a. Package limited.

b. Duty cycle \leq 1 %.

c. When mounted on 1" square PCB (FR-4 material).

d. See SOA curve for voltage derating.

* Pb containing terminations are not RoHS compliant, exemptions may apply.

						B VBse: VBsemi
SPECIFICATIONS (T _J = 25 °C	, unless oth	erwise noted)				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static		•				
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			v
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 1		- 3	v
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current		V _{DS} = - 30 V, V _{GS} = 0 V			- 1	
	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 125 °C			- 50	μA
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 175 °C			- 250	
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			A
					1	

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Static		·					
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30				
Gate Threshold Voltage	V _{GS(th)}	$V_{GS(th)}$ $V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$			- 3	V	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA	
	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 125 °C			- 50	μA	
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 175 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			А	
		V _{GS} = - 10 V, I _D = - 30 A		0.009			
Drain Course On Chata Desistance?		V _{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C		0.012		0	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 30 A, T _J = 175 °C		0.013		Ω	
		V _{GS} = - 4.5 V, I _D = - 20 A		0.011			
Forward Transconductance ^a	g _{fs}	V _{DS} = - 15 V, I _D = - 75 A	20			S	
Dynamic ^b	•	·		•			
Input Capacitance	C _{iss}			4000		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = - 25 V, f = 1 MHz		1565			
Reversen Transfer Capacitance	C _{rss}			715			
Total Gate Charge ^c	Qg			160	240	nC	
Gate-Source Charge ^c	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 75 A		32			
Gate-Drain Charge ^c	Q _{gd}			30			
Turn-On Delay Timeº	t _{d(on)}			25	40		
Rise Time ^c	t _r	V_{DD} = - 15 V, R _L = 0.2 Ω		225	360		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ - 75 Å, V_{GEN} = -10 V, R_g = 2.5 Ω		150	240	– ns	
Fall Time ^c	t _f			210	340		
Source-Drain Diode Ratings and Cha	racteristics ^b ((T _C = 25 °C)		•			
Continuous Current	Is				- 70		
Pulsed Current	I _{SM}				- 240	- A	
Forward Voltage ^a	V _{SD}	I _F = - 75 A, V _{GS} = 0 V		- 1.2	- 1.5	V	
Reverse Recovery Time	t _{rr}			55	100	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 75 A, dl/dt = 100 A/μs		2.5	5	А	
Reverse Recovery Charge	Q _{rr}			0.07	0.25	μC	

Notes:

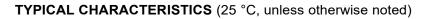
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

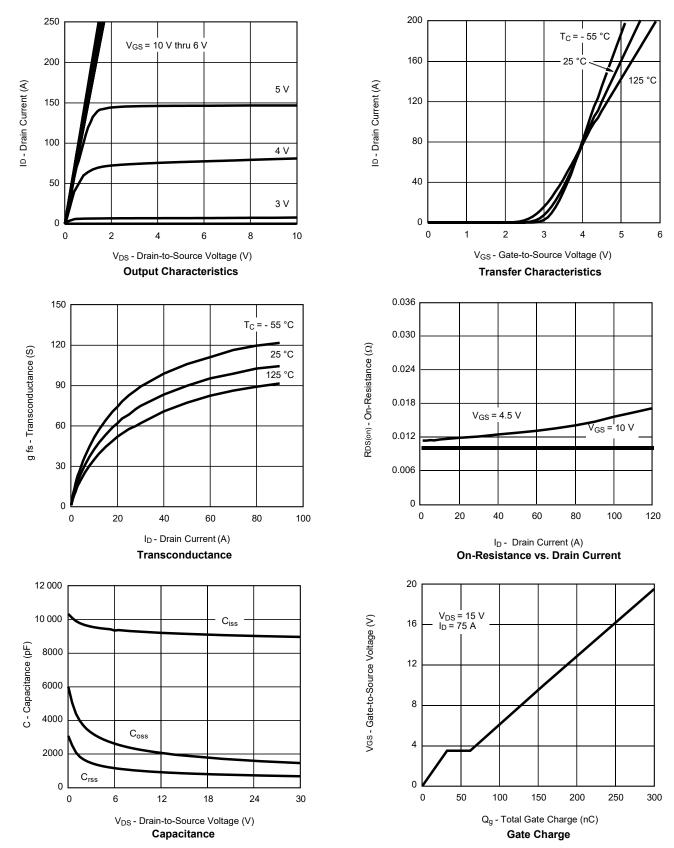
b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

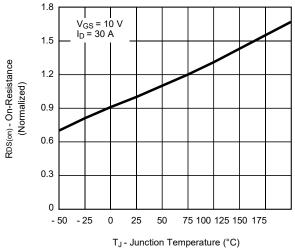




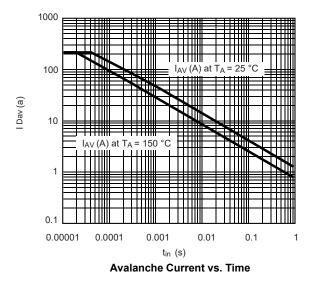


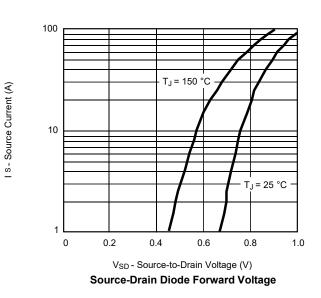


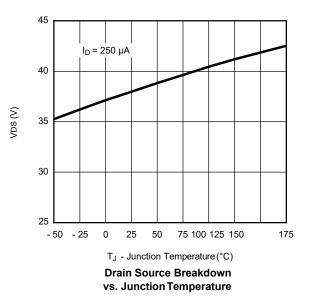
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



On-Resistance vs. Junction Temperature

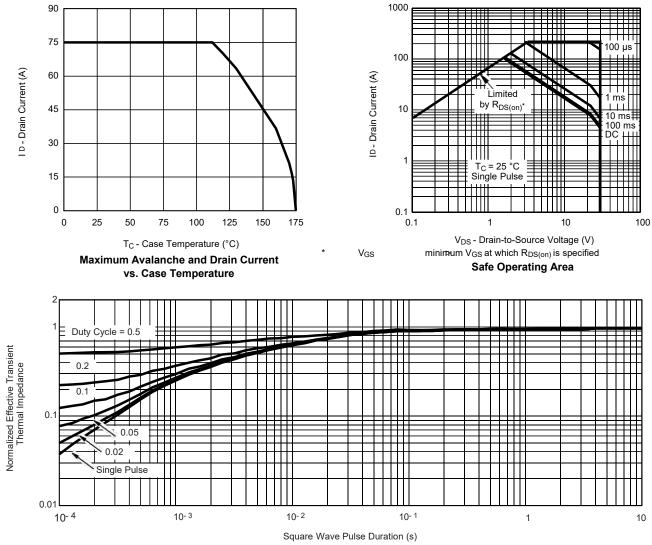








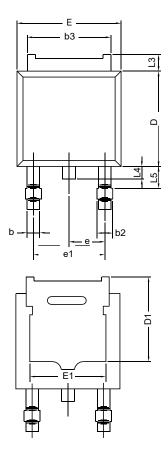
THERMAL RATINGS

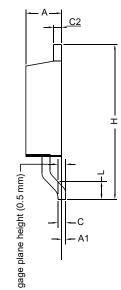


Normalized Thermal Transient Impedance, Junction-to-Case



TO-252AA CASE OUTLINE





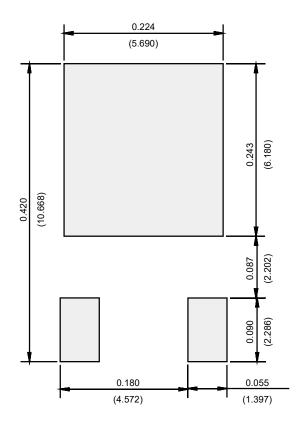
	MILLIN	IETERS	INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
E	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28	BSC	0.090 BSC			
e1	4.56	BSC	0.180 BSC			
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347						

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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